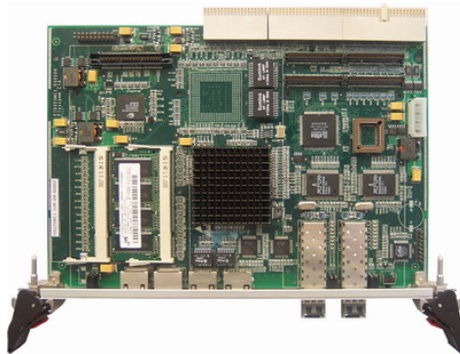


Flexcomm FIDS23MC1 System

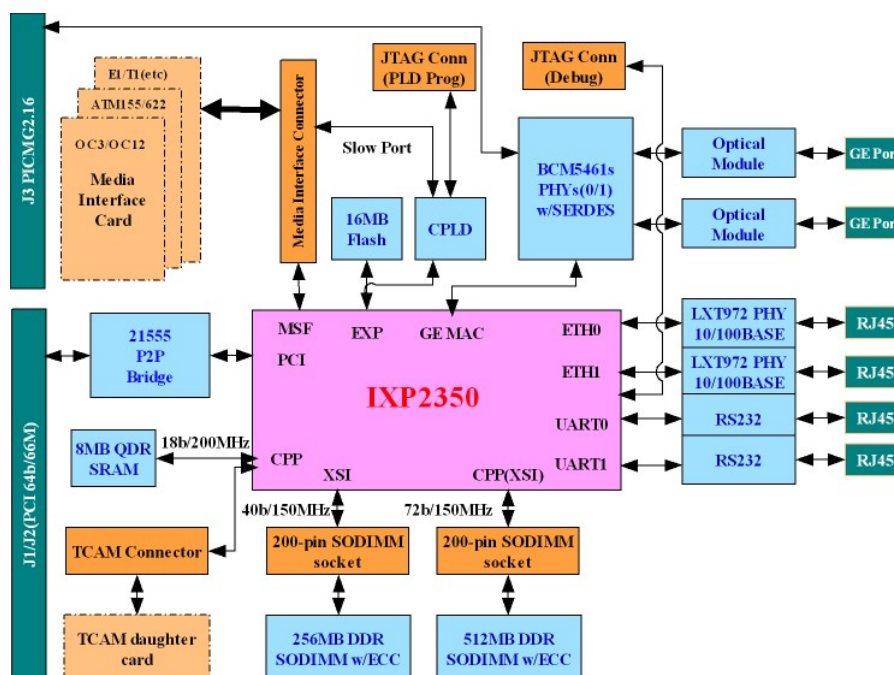
Gigabit PICMG2.16 board for Networking/Firewall



Product Overview

Designed and developed by Flexcomm, FIDS23MC1 is cost effective while integrated with lush functions and production-ready reference platform. It optimizes the performance and scalability of Intel IXP2350 network processor by utilizing its prevailing, parallel and programmable multi micro-engines. With Flexcomm's inevitable experience in software support of various reference designs, FIDS23MC1 reference platform enables customers to launch fast time-to-market custom product with lower cost and minimal development risk.

Functional Block Diagram



Product Highlights

- Low cost cPCI 2.16 form factor board
- 2 on-board Gigabit Ethernet ports on front panel (fiber), can also be connected via cPCI 2.16 backplane
- Expansion capability for media interface cards
- Linux BSP patch, Redboot and diagnostic software provided and supported by Flexcomm
- Application programmed in Flash memory to provide reference application of 2GE IPv4 throughput, 2GE IPv4 forwarding
- Intel SDK support includes core components, resource manager, example of ME code supported by Flexcomm
- Optimized BOM and schematic
- ATM155M daughter card developed by Flexcomm (*Optional*)

Hardware Features Definition

Processor	900/900M(900/600M) Intel® IXP2350 network processor
Flash	16MB StrataFlash, soldered to main board
SRAM	4MB QDR SRAM, soldered to main board
DRAM	512M CPP DDR DRAM (expandable to 2G) via SODIMM
	256M XSI DDR DRAM (expandable to 1G) via SODIMM
Console Ports	Two 10/100 Fast Ethernet ports and Two UART console ports
Consumption	Maximum 25Watt
Others	Redboot and diagnostic binary code in flash
	MSF expansion to support OC3/12, T1/E1 applications etc
	ATM155M daughter card developed by Flexcomm (<i>Optional</i>)
	2 Gigabit Ethernet based on Broadcom BCM5461s, fiber support at front panel on FIDS23MC1 board, can also switch to cPCI2.16 backplane
Dimension	233mmx160 mm, standard CPCI 6U board